3. (Amended) The [mount] mounting method as claimed in claim 1, wherein [the] said liquid is inactive to said device and said substrate.

4. (Amended) The [mount] mounting method as claimed in claim 1, wherein said device is an optical device.

5. (Amended) The [mount] mounting method as claimed in claim 1, wherein said device is a semiconductor device.

6. (Amended) The [mount] mounting method as claimed in claim 1, wherein said substrate is a semiconductor substrate.

7. (Amended) The [mount] mounting method as claimed in claim 1, wherein said substrate is a substrate for mounting an electric element.

8. (Amended) The [mount] mounting method as claimed in claim 1, wherein said substrate is a ceramic substrate.

9. (Amended) The [mount] mounting method as claimed in claim 1, wherein said substrate is a printed circuit board.

10. (Amended) A method of joining a substrate electrode formed on a substrate and a device electrode formed on a device to each other by solder to mount [the] said device on [the] said substrate, comprising the steps of:

attaching a solder piece to [the] said substrate electrode;

melting [the] said solder piece while said solder piece is at least partially submerged in a liquid to form a solder bump having an adhered surface and an opposite surface;

[matching the substrate electrode having the solder bump formed thereon with the device electrode and disposing the]

pre-positioning said device so as to contact said opposite surface of said solder bump [confront the substrate] while said device is at least partially submerged in [the] said liquid;

positioning [the] said device electrode to [the] said substrate electrode by surface tension of [the melted] said solder bump when [the] said solder bump is melted and while said device is at least partially submerged in [the] said liquid and at least partially supported by a buoyant force [to join the] thereby joining said device electrode and [the] said substrate electrode to each other; and then

solidifying [the] said solder bump.

11. (Amended) The method as claimed in claim 10, wherein as [when the] said solder piece is melted to form [the] said solder bump, [ultrasonic] a vibration is applied to [the] said solder piece [through the] while said solder piece is at least partially submerged in said liquid.

12. (Amended) The method as claimed in claim 10, wherein when [the] said solder bump is melted while said solder bump is at least partially submerged in [the] said liquid to join [the] said device electrode and [the] said substrate electrode to each other, [ultrasonic] a vibration is applied to [the] said solder bump [through the] while said device is at least partially submerged in said liquid.

13. (Amended) The method as claimed in claim 10, wherein [the] said liquid is inactive to said solder, said device and said substrate.

Please add the following new claims:

--20. The method as claimed in claim 2, wherein said vibration is applied ultrasonically.

21. The method as claimed in claim 11, wherein said vibration is applied ultrasonically.

22. The method as claimed in claim 12, wherein said vibration is applied ultrasonically.

23. The method as claimed in claim 1, wherein the joining of said device to said substrate is performed while a vibration is applied ultrasonically through said liquid to said solder disposed in said liquid.